

Base Materials

<i>Laminates and Copper Foils</i>	Standard High Yield	Advanced Reduced Yield	Engineering Low Yield	Notes
Flex – Adhesiveless Polyimide	DuPont AP Family Kapton®			
Flex – Adhesive + Polyimide	DuPont LF and FR families Pyralux®			
Flex – High Speed Laminate	---	DuPont TK		
Flex – High Speed Bondply / Coverlay		Taconic fastRise EZ		
Flex – Shielding Film	Tatsuta SF-PC5500			
Rigid FR4 Laminate & Prepreg	Isola FR406, Isola FR370HR			
Rigid Polyimide Laminate & Prepreg	Isola, Arlon, Hitachi			
Rigid Non Woven Aramid Epoxy	---	Arlon 55NT		
Rigid Non Woven Aramid Polyimide	---	Arlon 85NT		
Rigid High Speed Laminate	---	Rogers RO4000 Series		
Copper ⅛ oz ED	---	✓	✓	
Copper ¼ oz ED	✓	✓	✓	
Copper ½ oz to 2 oz RA and ED	✓	✓	✓	
Copper 3-20 oz RA and ED	---	✓	✓	
Minimum Dielectric Thickness Flex Cores	.001"			
Minimum Dielectric Thickness Rigid Cores	.003"	.002"		
Maximum PCB Thickness	.093"	.125"	.125"	